



Title of Change:	General Announcement of LOGO replacement of former Fairchild products by ON Semiconductor Logo.														
Effective Date:	Starting October 30th, 2017 (depending on inventories availability)														
Contact information:	Contact your local ON Semiconductor Sales Office or < fairchild_questions@onsemi.com >														
Type of notification:	ON Semiconductor will consider this change accepted.														
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☒ Other: LOGO change														
Change Sub-Category(s): ☐ Manufacturing Site Change/Addition ☐ Manufacturing Process Change ☐ Material Change ☐ Product specific change ☐ Datasheet/Product Doc change ☐ Shipping/Packaging/Marking ☒ Other: LOGO change on part marking															
Sites Affected: ☐ All site(s) ☒ Not applicable ☐ ON Semiconductor site(s) ☐ External Foundry/Subcon site(s) Select site: Select site:															
Description and Purpose: On Semiconductor acquired Fairchild Semiconductor on September 19th, 2016. As part of the integration, ON Semiconductor is replacing the "Fairchild" Logo on the product marking of the former Fairchild product portfolio with the ON Semiconductor Logo. For Molded Packaged parts, the "FAIRCHILD" name may be removed over time (part depending). The rest of the marking will not change. <table border="1" style="width: 100%;"> <thead> <tr> <th></th> <th>Standard Package Parts</th> <th>Molded Packaged Parts</th> </tr> </thead> <tbody> <tr> <td>Example of current marking with Fairchild logo.</td> <td></td> <td></td> </tr> <tr> <td>Example of marking after the change, with logo replaced by On Semiconductor logo.</td> <td></td> <td></td> </tr> <tr> <td>For Molded Packaged parts, the "FAIRCHILD" name may be removed over time (part depending).</td> <td>n/a</td> <td></td> </tr> </tbody> </table> This change will be effective around system integration, which is currently scheduled for Monday, October 30th, 2017. This means that you can start receiving parts with the new logo after October 30th, 2017, depending on inventories availability. If customers have questions regarding the system integration, please email the questions to <Fairchild_questions@onsemi.com>					Standard Package Parts	Molded Packaged Parts	Example of current marking with Fairchild logo.			Example of marking after the change, with logo replaced by On Semiconductor logo.			For Molded Packaged parts, the "FAIRCHILD" name may be removed over time (part depending).	n/a	
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List of Affected Part(s):

This is a General Announcement. General Announcements do not contain a specific list of affected devices. ON Semiconductor uses these announcements when all or no devices are affected.